

LISTING OF CLAIMS

This listing of the claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A process for forming a printed circuit board ~~formed by the process~~ comprising the steps of:

forming a conductor core containing a thin base of electrically conductive material and areas of thick conductive material, the thick conductive material in a predetermined pattern of conductor traces extending laterally on the thin base;

bonding the conductor core to a sublayer of electrically insulating material to create a flat laminate, wherein the areas of thick conductive material are positioned adjacent to and are covered by the sublayer; and,

forming predetermined printed circuits having both thick conductor traces formed from the thick conductive material and fine resolution traces formed from the thin base by removing conductive material from the flat laminate that does not comprise said predetermined printed circuits to form the predetermined printed circuits.

2. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein the conductor core and predetermined printed circuits comprise copper.

3. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein forming of the conductive core further comprises electrolytically depositing the areas of thick electrically conductive upon the thin electrically conductive base.
4. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein the sublayer of electrically insulating material comprises sheets of glass fiber reinforced with resin that is dried but not cured.
5. (cancelled)
6. (Currently Amended) The process ~~printed circuit board~~ of claim 1, wherein the bonding is performed at sufficient temperature and for a sufficient period of time to enable full and complete curing of the resins in the insulating sublayer.
7. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein removing of conductive material is accomplished through chemical etching.
8. (Currently Amended) The process ~~printed circuit board~~ of claim 1 further comprising applying a solder mask coating over predetermined areas of the printed circuit board.
9. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0020 inches.

10. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0007 inches.

11. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein said areas of thick conductive material are of a thickness in the range of 0.004 inches to 0.020 inches in predetermined pattern of conductor traces.

12. (Currently Amended) The process ~~printed circuit board~~ of claim 1 wherein said areas of thick conductive material are of a thickness in the range of 0.004 inches to 0.010 inches in a predetermined pattern of conductor traces.

13 -24 (Cancelled).

25. (Currently Amended) A process for making a printed circuit core suitable for use as a component of a multilayer printed circuit board ~~formed by the process~~ comprising the steps of:

forming a conductor core comprising a thin base of electrically conductive material and areas of thick conductive material , the thick conductive material in a predetermined pattern of conductor traces extending laterally on the thin base;

bonding the conductor core to a sublayer of electrically insulating material creating a flat laminate, wherein the areas of thick conductive material are positioned adjacent to and are covered by the sublayer; and,

removing conductive material from the flat laminate that does not comprise said predetermined printed circuits thereby forming predetermined printed circuits having both thick conductor traces formed from the thick conductive material and fine resolution traces formed from the thin base.

26. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein the conductor core and predetermined printed circuits comprise copper.

27. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein forming of the conductive core further comprises electrolytically depositing the areas of thick electrically conductive upon the thin electrically conductive base.

28. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein the sublayer of electrically insulating material comprises sheets of glass fiber reinforced with resin that is dried but not cured.

29. (Currently Amended) The process ~~printed circuit core~~ of claim 28 wherein the bonding of the conductor core to the sublayer of electrically insulating material is performed by hot pressing the conductor core to the sublayer.

30. (Currently Amended) The process ~~printed circuit core~~ of claim 29 wherein the hot pressing is performed at sufficient temperature and for a sufficient period of time to enable full and complete curing of the resins in the insulating sublayer.

31. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein removing of conductive material is accomplished through chemical etching.

32. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0020 inches.

33. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein said thin base is of a thickness in the range of 0.0003 inches to 0.0007 inches.

34. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.020 inches.

35. (Currently Amended) The process ~~printed circuit core~~ of claim 25 wherein said areas of thick conductive material are in the range of 0.004 inches to 0.010 inches.